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Materials Declaration

Company Name : Fox Electronics
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Completed by Bruce Clark
Date : August 31, 2005
Product Family : DIP14 Oscillator (F1100ELF series, F5C-2ELF series)

	Material Name	Component	Content (mg)	Content (w t %)	(CAS Number)
Cover	Stainless Steel	Nickel (Ni)	65.44	1.7684%	7440-02-0
		Chromium (Cr)	145.92	3.9433%	7740-47-3
		Iron (Fe)	575.95	15.5644%	7439-89-6
		Manganese (Mn)	8.320	0.2248%	7439-96-5
		Silicon (Si)	3.840	0.1038%	7440-21-3
		Carbon C	0.352	0.0095%	7440-44-0
		Sulphur (S)	0.008	0.0002%	7704-34-9
		Phosphorus (P)	0.168	0.0045%	7723-14-0
Header	Iron Alloy	Iron (Fe)	2197.580	59.3872%	7439-89-6
		Carbon C	1.100	0.0297%	7440-44-0
		Silicon (Si)	0.220	0.0059%	7440-21-3
		Manganese (Mn)	5.070	0.1370%	7439-96-5
		Phosphorus (P)	0.308	0.0083%	7723-14-0
		Sulphur (S)	0.110	0.0030%	7704-34-9
	+ PTH Glass	Glass Frit	13.400	0.3621%	65997-18-4
	+ Standoff Glass	Glass Frit	46.800	1.2647%	65997-18-4
	+ Kovar leads	Iron (Fe)	25.25	0.6824%	7439-89-6
		Nickel (Ni)	13.950	0.3770%	7440-02-0
		Cobalt (Co)	8.200	0.2216%	7440-48-4
	+ Solder Dip	Tin (Sn)	4.825	0.1304%	7440-31-5
		Silver (Ag)	0.150	0.0041%	7440-22-4
		Copper (Cu)	0.025	0.0007%	7440-50-8
H/I C	IC Die	Aluminum (Al)	0.0016	0.00004%	7429-90-5
		Molybdenum (Mo)	0.0002	0.000006%	7439-98-7
		Silicon (Si)	0.8400	0.02%	7440-21-3
		Titanium (Ti)	0.00037	0.000010%	7440-32-6
		Arsenic (As)	0.00000812	0.00000022%	7440-38-2
		Chromium (Cr)	0.000000738	0.00000002%	7440-47-3
	Mold	Epoxy resin	4.6800	0.126%	129915-35-1
		Organic Phosphorus	0.4160	0.011%	
		Metal Hydroxide	1.8200	0.049%	
		Silica (SiO ₂)	41.2880	1.116%	60676-86-0
		Carbon Black	0.1570	0.004%	1333-86-4
		Phenol	3.6700	0.099%	9003-35-4
	Gold	Gold (Au)	0.1400	0.004%	7440-57-5
	Adhesive	Silver (Ag)	0.037750	0.001020%	7440-22-4
		Epoxy Resin	0.012250	0.0003310%	129915-35-1
	Leadframe	Copper (Cu)	18.5250	0.5006%	7440-50-8
		Silver (Ag)	0.4750	0.0128%	7440-22-4
	Leadframe Plating	Tin (Sn)	0.676000	0.0183%	7440-31-5
		Silver (Ag)	0.016900	0.0005%	7440-22-4

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	Ceramic Substrate	Alumina (Al ₂ O ₃)	379.4490	10.2542%	1344-28-1
		Silicon Oxide (SiO)	9.4960	0.2566%	11126-22-0
		Titanium Oxide (TiO ₂)	0.0399	0.001078%	13463-67-7
		Iron Oxide (Fe ₂ O ₃)	0.2390	0.006459%	1309-37-1
		Calcium Oxide (CaO)	1.4400	0.038914%	1305-78-8
		Sodium Oxide (Na ₂ O)	0.9580	0.025889%	1313-59-3
		Magnesium Oxide (MgO)	3.7500	0.101340%	1309-48-4
		Potassium Oxide (K ₂ O)	3.1920	0.086260%	12136-45-7
	Conductor	Silver (Ag)	5.9500	0.160792%	7440-22-4
		Glycol Ethyl Ether	0.3500	0.009458%	109-87-5
		Terpineol	0.3500	0.009458%	8000-41-7
		Di(2-ethylhexyl) Phthalate	0.0700	0.001892%	117-81-7
	Conductor Overglaze	Resin, Hydrogenated, methyl ester	0.3600	0.009729%	8050-15-5
		Glass Frit	9.3600	0.252944%	65997-18-4
		Glycol Ethyl Ether	0.6000	0.016214%	109-87-5
		Terpineol	1.0800	0.029186%	8000-41-7
		Di(2-ethylhexyl) Phthalate	0.4800	0.012971%	117-81-7
		Nickel (Ni)	0.1200	0.003243%	7440-02-0
	Chip Cap	Barium Titanate (BaTiO ₃)	1.1994	0.032412%	12047-27-7
		Nickel (Ni)	0.0024	0.000065%	7440-02-0
		Copper (Cu)	0.0001	0.000003%	7440-50-8
		Nickel (Ni) (PLATING)	0.0001	0.000003%	7440-02-0
		Tin (Sn) (PLATING)	0.0001	0.000003%	7440-31-5
	SMD Solder	Tin (Sn)	15.4400	0.417249%	7440-31-5
		Silver (Ag)	0.5600	0.015133%	7440-22-4
	Substrate attach solder	Tin (Sn)	19.3000	0.521561%	7440-31-5
		Silver (Ag)	0.6000	0.016214%	7440-22-4
Copper (Cu)		0.1000	0.002702%	7440-50-8	
Crystal	Crystal	Silicon Dioxide (SiO ₂)	40.00	1.08%	14808-60-7
	Electrode	Silver (Ag)	6.000	0.1621%	7440-22-4
	Blank Adhesive	Silver (Ag)	8.16000	0.220515%	7440-22-4
		Silicon (Si)	2.040000	0.055129%	7440-21-3
TOTAL			3700.4	100.00%	